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ABSTRACT OF THE DISCLOSURE

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Stacked Package for Integrated Circuits

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A space-saving integrated circuit package employs two printed circuit boards joined together, the upper board having an integrated circuit attached by flip-chip technology and the lower board having a cavity for holding an integrated circuit that is located beneath the upper integrated circuit, the lower integrated circuit being bonded to the bottom of the upper board below the upper integrated circuit and electrically connected to wiring on the lower surface of the lower board by wire bond connections.